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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Sei TSUNODA, et al.

:

: GROUP: 1751

SERIAL NUMBER: 09/942,626

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FILED: August 31, 2001

FOR: LOW DIELECTRIC CONSTANT MATERIAL HAVING THERMAL  
RESISTANCE, INSULATION FILM BETWEEN SEMICONDUCTOR  
LAYERS USING THE SAME, AND SEMICONDUCTOR DEVICE

SECOND REQUEST

STATUS REQUEST

Honorable Commissioner of Patents & Trademarks  
Alexandria, Virginia 22313

SIR:

The Patent Office is respectfully requested to advise the undersigned of the approximate date a first Official Action will be issued in this Application.

A duplicate of this request is enclosed for your convenience.

Respectfully submitted,

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